



The European Institute for the PCB Community

EIPC SPEeDNEWS

*The Weekly On-Line Newsletter from the European Institute of Printed Circuits.
Issue 27- September 2021*

NEWS FROM THE EIPC

WECC REPORT 2020

The WECC Global PCB Production Reports are available only from the participating associations to their members.

FREE of charge EIPC membership service!
The reports are not for sale.

The World Electronic Circuits Council (WECC) is a strategic partnership formed in 1998 by the major industry associations serving member companies in the global electronic circuits industry.

Its purpose is to increase the global influence and effectiveness of its member organizations for the benefit and improvement of the industry.

The member associations cooperate on standards, market research, marketing, resource development, environmental issues, world trade, and economic and political affairs.

The member organisations of WECC formed a working group in 2005 to pool their statistical resources and produce a global statistical report on printed circuit board (PCB) production for the benefit of their members. This group became the WECC Statistics and Market Committee.

For your copy please contact EIPC – Kirsten Smit-Westenberg, Executive Director, European Institute of Printed Circuits, KWestenberg@eipc.org



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NEWS FROM ISRAEL

New appointments at PCB Technologies

PCB Technologies, a recognized All in One electronic solutions provider, has recently recruited two executives for key roles to support its global expansion strategy:

Mr. Yaniv Maydar has joined our TEAM of LEADERS and was appointed as our new V.P. of R&D and Innovation.

With over two decades of experience in leading roles such as V.P. R&D at TeraGroup, Miniaturization & Technology Director at IAI-Elta Systems, and mechanical design group manager at Modumobile, Yaniv brings vast experience in various fields within the Electronic Packaging Industry, where he led groundbreaking technological solutions. Yaniv will be in charge of our top notch engineering and manufacturing team and will lead the company's technological leadership strategy.

Mr. Reuven Avni has joined our TEAM of LEADERS and was appointed as our new Chief Information Officer (CIO).

Reuven has over two decades of experience in leading roles such as CIO at Given Imaging (Medtronic), Director of Municipal Domain at Ness Technologies and Programs Manager and SAP expert at Nestle. His main focus will be on the implementation of information systems and infrastructure as well as the acceleration of automated business processes, all aimed at enhancing our responsiveness to customers' needs.

We're excited to have them both on board and wish them much success in their new positions.

For more information, visit <https://pcb-technologies.com/>.



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NEWS FROM THE UK



IPower3 - Electronic Packaging for net zero

**One Day Conference on Thursday 2nd December 2021
at the Advanced Propulsion Centre, University of
Warwick**

Conference Topics - iPower3

Materials - Semiconductor and Passive Devices

- SiC Devices
- GaN devices
- Si Devices
- Emerging WBG Devices
- Capacitors
- Inductors
- Resistors

Packaging and Interconnect

- Die Attach
- Sintering
- Wire/ribbon Bonding
- Laser Welding
- Encapsulation
- Embedding Devices
- Novel Materials
- Thermal

Power Generation, Conversion and Distribution

- Module Characterisation
- Environmental Testing
- Lifetime and Reliability Prediction
- Degradation and Failure Mechanisms
- Switching Performance

Energy Storage

- Batteries
- Fuel Cell
- Hydrogen
- Ammonia

IMAPS-UK invites Abstracts which describe the latest advancements in electronic package design, materials, processes, next level integration and performance while maintaining reliability, sustainability, manufacturability and cost-competitiveness in power generation, conversion, distribution and energy storage applications.

THOSE WISHING TO PRESENT THEIR WORK AT IPOW3 SHOULD
SUBMIT AN ABSTRACT OF 200-300 WORDS BY FRIDAY 10TH
SEPTEMBER 2021, ELECTRONICALLY TO: OFFICE@IMAPS.ORG.UK

[Further Information on Call for Proposals for iPower3 - Click Here](#)

For Any other details or information Please contact:

IMAPS-UK Secretariat

125 High Street Chesterton, Cambridge, UK

Tel: +44 0131 2029004

e-mail: Office@imaps.org.uk

Institute of Circuit Technology Journal

The Institute have asked if we might include the links to their Journal, and we are honoured to do so. There are some very good articles that will hopefully be of benefit to the industry.

[ICT Journal Vol 14 No 2](#)

Contents

[Editors Introduction](#)

[Lynn Houghton](#)

[1 Editorial - Recover to the New Normal, Paul Goodfellow](#)

[2 Calendar of Events](#)

[3 New PCB Material for Demanding High Temperature and High Voltage Requirements of the Rapidly Growing Automotive EV Market, Anna Graf and Michael J Gay](#)

[4 Choosing the Right Materials is Tougher Than Ever, Mark Goodwin](#)

[5 Ultra Low Profile Copper for Very Low Loss Material, Thomas Devahif](#)

[6 ICT Webinar: , Pete Starkey](#)

[7 Annual Foundation Course 2021, Bill Wilkie](#)

[8 PCB Fabricators Group Update. Matthew Beadel](#)

[9 Industry News: Macdermid Alpha, CC Electronics, Eurotech, Merlin PCB](#)

[10 Members News: Maurice Hubert, Foundation Course Attendees, Exception PCB- Lisa Trust](#)

[11 Membership News - New Members and Grading](#)

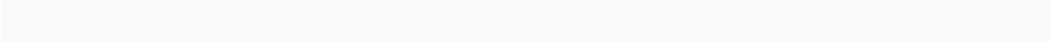
[12 Corporate Members](#)

[13 Council Members](#)

[14 Editors Notes](#)

[15 Lynn Houghton](#)

The ICT Journal is a public document and you are welcome to share it with your colleagues.



News from
WECC members



Issue 27 – September 2021

NEWS FROM THE IPC



Economic recovery continues along a bumpy path. In this [month's economic outlook report](#), IPC's Chief Economist Shawn DuBravac offers five key observations:

1. Global demand remains strong, but we are starting to see some early signs that demand might be slowing.
2. Even with demand slowing, backorders remain high and inventories remain low which should keep manufacturers busy for the foreseeable future.
3. Stimulus, both fiscal and monetary, is waning which will be a headwind on spending.
4. Prices remain high and will move inversely to demand, but money supply is up significantly suggesting prices will likely remain elevated into next year.
5. COVID has become a sledgehammer to confidence.

In addition to observations from Shawn DuBravac, you will also find U.S. and European data on economic growth, employment, consumer sentiment, manufacturers' sentiment (PMI), manufacturing capacity utilization and end markets for electronics.

DuBravac is available for interviews. Contact Sandy Gentry at SandyGentry@ipc.org with interview requests.

[READ AUGUST REPORT](#)



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International Diary

2021

EIPC @ FED Conference

Bamberg

16 & 17 September

11th EIPC Technical Snapshot Webinar

Registrations via www.eipc.org

22 September

KPCA Korea

6-8 October

12th EIPC Technical Snapshot Webinar

Registrations via www.eipc.org

October

EIPC @ Productronica 2021

Stand B3-529

Messe München

16-19 November

TPCA Taiwan

21-23 December